



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-12-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TSLY*MD6NB6F	TSLY*MD6NB6F	A	Z8GA	2015-12-04
Amount	UoM	Unit type	ST ECOPACK Grade	
4900.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	4.3-2.77-2	4	Through-hole	
Comment	Package: TO 247 MAX			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TSLY*MD6NB6F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	109.351	mg	supplier	die	Silicon (Si)	7440-21-3		106.135	mg	970590	21660
				supplier	metallization	Aluminium (Al)	7429-90-5		1.541	mg	14092	314
				supplier	Passivation	Silicon Nitride	12033-89-5		0.374	mg	3420	76
				supplier	Passivation	Silicon Oxide	7631-86-9		0.531	mg	4856	108
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.038	mg	348	8
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.541	mg	4947	110
Leadframe	Copper & its alloys	2649.791	mg	supplier	back side metallization	Silver (Ag)	7440-22-4		0.191	mg	1747	39
				supplier	alloy	Copper (Cu)	7440-50-8		2645.444	mg	998359	539887
				supplier	alloy	Iron (Fe)	7439-89-6		1.218	mg	460	249
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		2.225	mg	840	454
				supplier	metallization	Nickel (Ni)	7440-02-0		0.836	mg	315	171
				supplier	metallization	Phosphorus (P)	12185-10-3		0.068	mg	26	14
Soft solder	Other organic materials	23.160	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	22.117	mg	954965	4514
				supplier	solder	Silver (Ag)	7440-22-4		0.580	mg	25043	118
				supplier	solder	Tin (Sn)	7440-31-5		0.463	mg	19991	94
				supplier	wire	Aluminium (Al)	7429-90-5		29.169	mg	1000000	5953
Encapsulation	Other organic materials	2080.792	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1810.289	mg	870000	369447
				supplier	mold compound	Epoxy resin	Proprietary		208.080	mg	100000	42465
				supplier	mold compound	Phenol resin	Proprietary		52.020	mg	25000	10616
				supplier	mold compound	Carbon Black	1333-86-4		10.403	mg	5000	2123
Connections coating	Solder	7.737	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		7.737	mg	1000000	1579